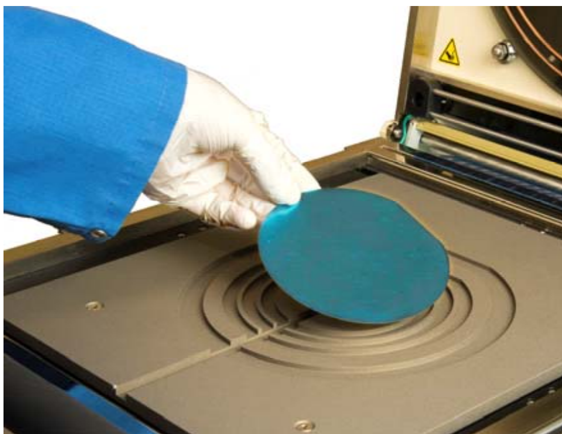
Model 3200 / 3250
Wafer / Backlap Tape Applicator

Features
- Cuts tape within .005” of edge of wafer
- Bubble free tape applicator
- Safe, accurate tape trimming system
- Vacuum stage wafer hold-down
- Adjustable, machine controlled roller pressure
- Manual tape feed

Options:
- Peeler
- Static eliminator
- Motorized take-up for tapes with liner



Model	**3200**	**3250**
Wafer Size:	3, 4, 5 & 6	4, 5, 6 & 8
Weight:	80 lbs	100 lbs
Height:	11”-12”	11”-25”
Length:	28”	32”
Width:	15”-21”	17”-23”

Vacuum: 25 in/Hg
Voltage: 100-120/220 VAC

SEC offers a complete line of dicing and back grinding tapes.

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